

Silicon N-Channel MOS Type (π-MOSVI)

2SK3868

Switching Regulator Applications

Unit: mm

• Low drain-source ON resistance: $R_{DS\ (ON)}$ = 1.3 Ω (typ.)

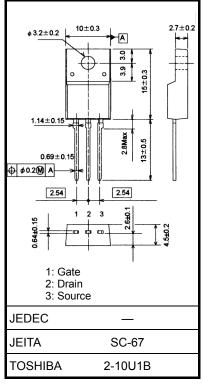
• High forward transfer admittance: |Y_{fs}| = 3 S (typ.)

• Low leakage current: $I_{DSS} = 100 \mu A (V_{DS} = 500 V)$

• Enhancement model: V_{th} = 2.0 to 4.0 V (V_{DS} = 10 V, I_D = 1 mA)

Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	500	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V_{DGR}	500	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	5	А	
	Pulse (t = 1 ms) (Note 1)	I _{DP}	20		
Drain power dissipation (Tc = 25°C)		PD	35	W	
Single pulse avalanche energy (Note 2)		E _{AS}	180	mJ	
Avalanche current		I _{AR}	5	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	3.5	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55 to 150	°C	



Weight: 1.7 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

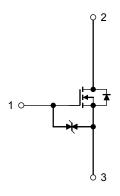
Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	3.57	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: $~V_{DD}=90~V,~T_{ch}=25^{\circ}C$ (initial), L = 12.2 mH, $I_{AR}=5~A,~R_{G}=25~\Omega$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.



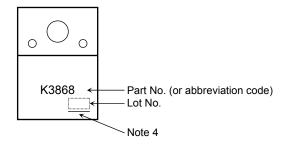
Electrical Characteristics (Ta = 25°C)

Char	racteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Gate-source brea	akdown voltage	V (BR) GSS	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain cutoff curre	ent	I _{DSS}	V _{DS} = 500 V, V _{GS} = 0 V	_	_	100	μА
Drain-source bre	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	500	_	_	V
Gate threshold vo	oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source ON	resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 2.5 A	_	1.3	1.7	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 2.5 A	1.5	3.0	_	S
Input capacitance		C _{iss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	550	_	pF
Reverse transfer capacitance		C _{rss}		_	7	_	
Output capacitance		Coss		_	70	_	
Switching time	Rise time	t _r	$V_{GS} = 0 \text{ for } \Omega$	_	10	_	
	Turn-on time	t _{on}		_	20	_	20
	Fall time	t _f		_	10	_	ns
	Turn-off time	t _{off}	V _{DD} ≃ 225 V Duty ≤ 1%, t _W = 10 μs	_	50	_	
Total gate charge		Qg			16	_	
Gate-source charge		Q _{gs}	$V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$	_	10	_	nC
Gate-drain charge		Q _{gd}			6		

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_		_	5	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	20	Α
Forward voltage (diode)	V _{DSF}	$I_{DR} = 5 A$, $V_{GS} = 0 V$			-1.7	V
Reverse recovery time	t _{rr}	$I_{DR} = 5 \text{ A}, V_{GS} = 0 \text{ V},$	_	150	_	ns
Reverse recovery charge	Qrr	dl _{DR} /dt = 100 A/μs		0.3	_	μС

Marking



Note 4: A line under a Lot No. identifies the indication of product Labels.

Not underlined: [[Pb]]/INCLUDES > MCV

Underlined: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]]

